

PCN – Process Change Notification

Change:	PA/SGP/SGGP/ILA/GLA/GGBLA Series Products
Date:	2016/09/08
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Affected Products

Model#	Part Number	Changes
PA Series	-	Amend Package. (follow MSL III)
SGP Series		
SGGP Series		
ILA Series		
GLA Series		
GGBLA Series		

Type of Change

- Hardware Modification
 Production Process Advance
 Others –Amend Package
-

Description of Change

- Amend Package (follow MSL III), in order to keep Taoglas SMT series products have good storage conditions before it using. The package need to be put desiccant and humidity indicator card into the vacuum bag. And, we will mark the package standard follow the MSL III level labels on the packaging carton.

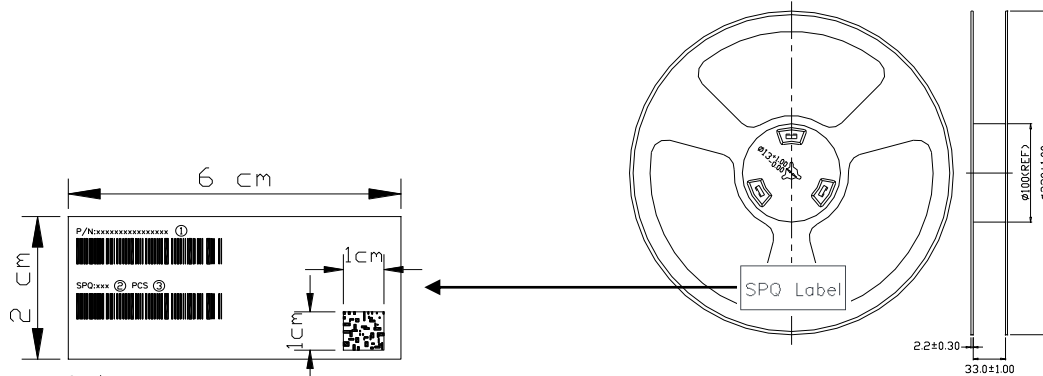
Schedule

2016, September, Taoglas will input this new packaging into productions.

Forecast Estimated Transition Date

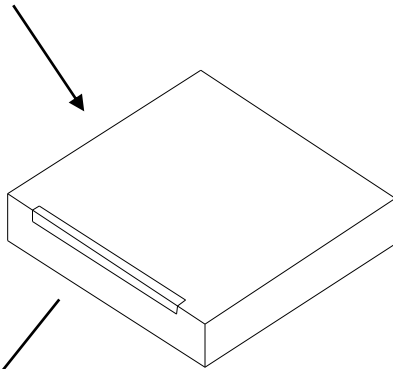
Sep/2016

Illustration of Change Old Package

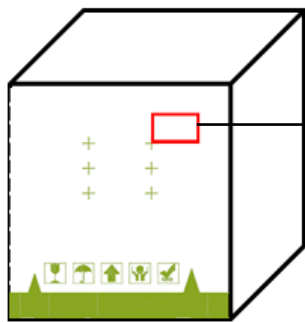


ⓄP/N: Taoglas的品號
 ⓄSPQ QTY: SPQ的數量
 ⓄUnit:每一數量的單位

Vacuum packaging



Carton-Inside

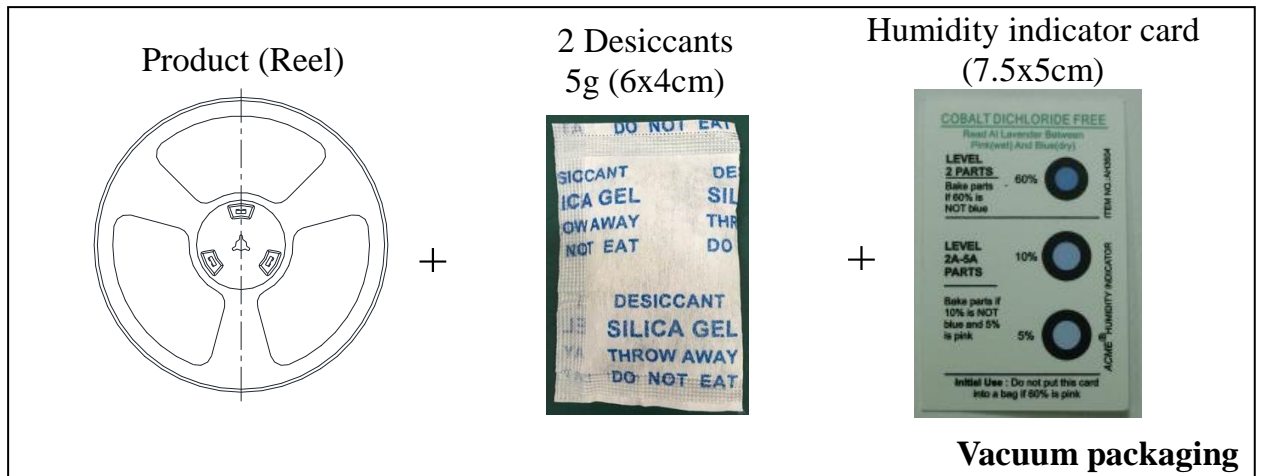


Carton



Shipping Label

New Package



Caution Label

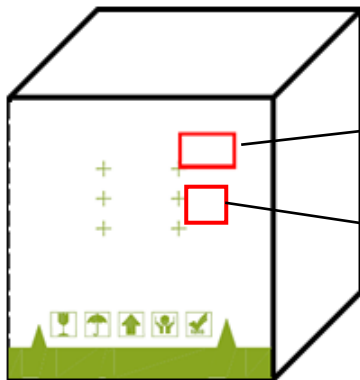
	Caution This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL 3 <small>If blank, see adjacent bar code label</small>
	<ol style="list-style-type: none"> Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH) Peak package body temperature: _____ $^{\circ}\text{C}$ <small>If blank, see adjacent bar code label</small> After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be: <ol style="list-style-type: none"> Mounted within: _____ hours of factory conditions <small>If blank, see adjacent bar code label</small> $\leq 30^{\circ}\text{C}/60\% \text{ RH}$, or Stored per J-STD-033 Devices require bake, before mounting, if: <ol style="list-style-type: none"> Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$ 3a or 3b are not met If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure 	
Bag Seal Date: _____ <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

SPQ Label



ⓅP/N: Taoglas的品號
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Carton-Inside



Carton

Shipping Label

MSID Label

